

DEC-02-2005 21:18

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Mezenner

Art Unit: 2873

Serial No.: 10/749,277

Examiner: Dinh, Jack

Filed: 31 December 2003

Docket No. TI-33824

For: VIA ADHESION IN MULTILAYER MEMS STRUCTURE

AMENDMENT

11 November 2005

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8 (a)	
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, Virginia, 22313-1450, or facsimile transmitted to the U.S. Patent and Trademark Office, on the date shown below.	
	11 Nov 2005
Charles A. Brill	Date

Dear Sir:

In response to the Examiner's Action mailed 12 July 2005, applicant amends as follows:

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